



## AT A GLANCE

Ultra-fast, low-loss and flexible electrical interconnects for opto-electrical packaging.



### Features

Polymer embedded electrical coplanar waveguides.

- Bandwidth > 200GHz
- Customized design
- mm to cm scale

### Applications

High speed flexible electrical chip to chip interconnect:

- Driver-to-LD
- PD-to-TIA

### Technical Background

Ultra-fast, low-loss and flexible electrical coplanar waveguides for interconnecting drivers to laser and photo detectors to transimpedance amplifiers (TIAs) with bandwidths exceeding 200 GHz.

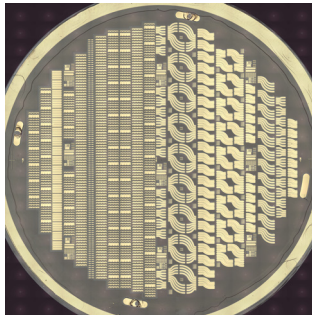
Fabricated on wafer scale.

Customized design available.

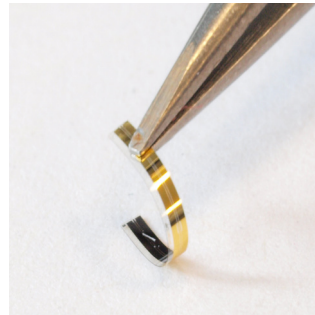
## References

International R&D projects  
 PHOENICS  
 POETICS  
 POLYNICES  
 QSNP  
 Qu-Test / Qu-Pilot  
 SPRINTER  
 TERA 6G  
 TERAMEASURE  
 TERAWAY  
 (funded by EU commission)

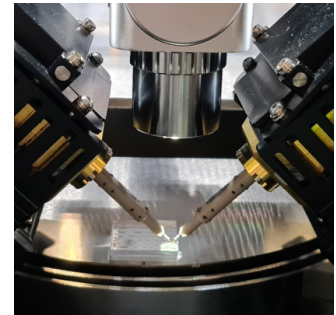
## Characteristics



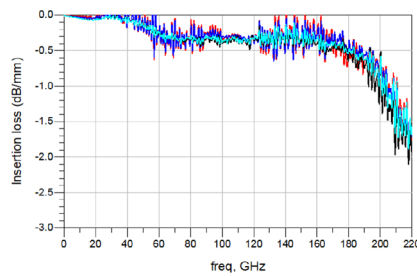
*Fabrication on wafer scale,  
 customized design*



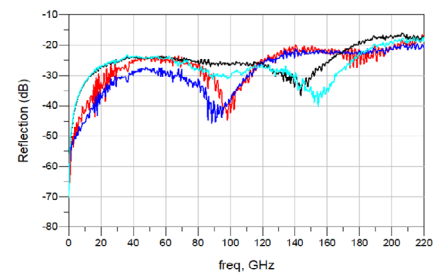
*Flexible electrical interconnects*



*RF characterization set-up*



*Transmission: >> 200 GHz*



*Reflection: <-20 dB*

## Applications

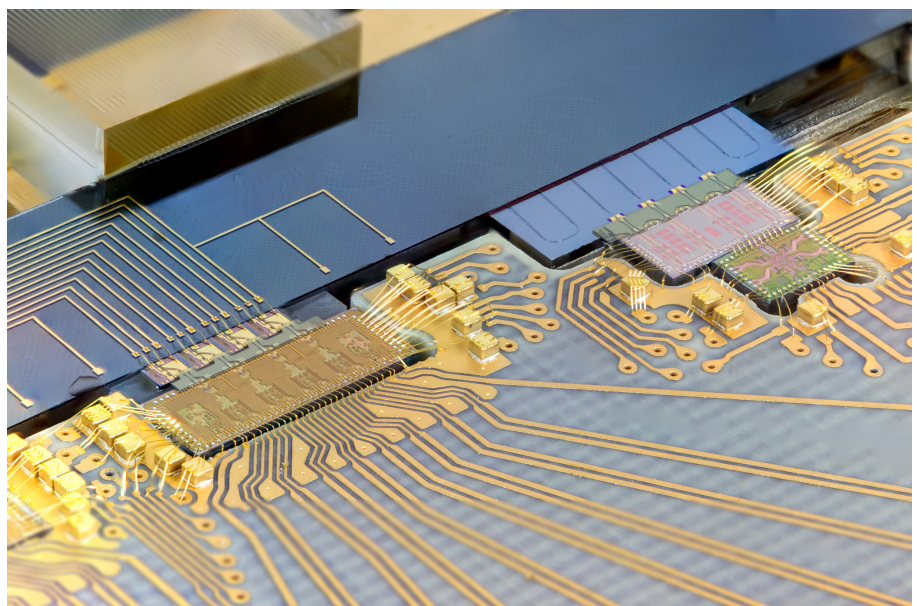


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*1.6 Tb/s optical transceiver with FlexLines for intra datacenter connectivity (EU POETICS).*